

ABSTRACT OF THE DISCLOSURE

The invention encompasses a method of treating a physical vapor deposition target. The target has a sputtering surface and a sidewall edge at a periphery of the sputtering surface. The method comprises pressing a tool against the sidewall edge to
5 form a distribution of imprints in the sidewall edge of the target. The tool is then removed from the sidewall edge, leaving the imprints extending into the sidewall edge. The invention also encompasses a physical vapor deposition target. The target includes a sputtering surface having an outer periphery, and a sidewall edge along the outer periphery of the sputtering surface. The sidewall edge has a repeating pattern of imprints
10 extending therein.